

AMENDMENTS TO THE CLAIMS

This following listing of claims replaces all prior listings, and all prior versions, of claims in the application:

LISTING OF THE CLAIMS:

1. (Currently Amended) An electronic component comprising:

a ceramic board containing glass; and

a conductor film stuck to the ceramic board,

wherein the conductor film is formed by firing a conductor paste, which does not contain any glass and which contains a silver particle having a specific surface area of $0.3 \text{ m}^2/\text{g}$ to $3.0 \text{ m}^2/\text{g}$ before the firing, at a temperature having a difference of $\pm 50^\circ\text{C}$ from a softening temperature of the glass, the conductor paste having been stuck on a glass ceramic sheet board which has not been sintered or has been sintered.

2. (Currently Amended) An electronic component comprising:

a ceramic board containing glass; and

a conductor film stuck to the ceramic board and containing silver,

wherein the glass intrudes into the conductor film from a surface on the ceramic board side and is not exposed on a surface of the opposite side of the ceramic board, and

wherein the conductor film is formed by firing a conductor paste, which does not contain any glass and which contains a silver particle having a specific surface area of $0.3 \text{ m}^2/\text{g}$ to $3.0 \text{ m}^2/\text{g}$ before the firing, at a temperature having a difference of $\pm 50^\circ\text{C}$ from a softening temperature of the glass, the conductor paste having been stuck on a glass ceramic sheet board which has not been sintered or has been sintered.

3. (Withdrawn) A method of manufacturing an electronic component which has a conductor film formed on a glass ceramic board, comprising the steps of:

a process for sticking a conductor paste containing a silver particle having a specific surface area of $0.3 \text{ m}^2/\text{g}$ to $3.0 \text{ m}^2/\text{g}$ and no glass onto a glass ceramic sheet board which has not been sintered or has been sintered; and

a process for firing the conductor paste at a temperature having a difference of ~~$\pm 50^\circ\text{C}$~~ $\pm 50^\circ\text{C}$ from a softening temperature of the glass and for forming the conductor film on the glass ceramic board.

4. (Currently Amended) An electronic component which has a conductor film formed on a glass ceramic board, formed by a method comprising the steps of:

sticking a conductor paste₁ containing a silver particle having a specific surface area of $0.3 \text{ m}^2/\text{g}$ to $3.0 \text{ m}^2/\text{g}$ in the conductor paste prior to firing, and no glass₁ onto a glass ceramic sheet board which has not been sintered or has been sintered; and

firing the conductor paste at a temperature having a difference of $\pm 50^\circ\text{C}$ from a softening temperature of the glass of the glass ceramic board and for forming the conductor film on the glass ceramic board.

5. (Previously Presented) An electronic component according to claim 1, wherein the conductor paste includes, in addition to silver, at least one selected from the group consisting of platinum and palladium.

6. (Previously Presented) An electronic component according to claim 5,

wherein the at least one selected from the group consisting of platinum and palladium is included in the conductor paste in an amount sufficient to prevent silver migration and solder leaching.

7. (New) An electronic component according to claim 1, wherein said glass of said ceramic board is a borosilicate glass.

8. (New) An electronic component according to claim 2, wherein said glass of said ceramic board is a borosilicate glass.

9. (New) An electronic component according to claim 4, wherein said glass of said glass ceramic board is a borosilicate glass.